



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260827001.1	PCN Issued	August 27, 2026
Qualification of TIPI as an additional Assembly site and BOM options for select devices		Sample request deadline:	October 26, 2026
		Estimated 1st ship date:	November 25, 2026
Sample requests received after October 26, 2026 will not be supported.			

Change type(s)
Assembly Site
Assembly Material
Packing/Shipping/Labeling

PCN Details

Description of Change:			
Texas Instruments is pleased to announce the qualification of TIPI as an additional Assembly Site for selected devices as listed below in the product affected section.			
Construction Differences are as follows:			
	Current Site		Additional Site
	CDAT	CDAT (New)	TIPI
Mount compound	4226215	4207123	8095733
Lead finish	Matte Sn	Matte Sn	NiPdAu
Lead frame material	Chip On Lead	Chip On Pad	Chip On Pad
Qual details are provided in the Qual Data Section.			
Reason for Change:	Supply Continuity		

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Physical aspects of the device have changed Request the Supporting Data Packet for more details on the changes			
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
	RoHS	REACH	Green Status	IEC 62474
	☒ No Change	☒ No Change	☒ No Change	☒ No Change
Changes to product identification resulting from this PCN:	Assembly Site Information			
	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
	TI Chengdu	CDA	CHN	Chengdu

	TI Philippines	PHI	PHL	Baguio City
Sample product shipping label (not actual product label):				
				

Products Affected:			
LSF0102DDFR	SN74AVC2T45DDFR	TCA39306DDFR	

Qualification Report
DDF Lead Frame & BOM change
Approve Date 19-August -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TCA39306DDFR	QBS Package Reference: TLV9061IDBVR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	3/228/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	3/228/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	3/15/0
FTY	E6	Final Test Yield	-	-	1/1/0	3/3/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TCA39306DDFR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hour

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2412-026

Qualification Report

DDF Offload from CDAT to TIPI

Approve Date 19-August -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC2T45DDFR	QBS Package Reference: TLV1805QDBVRQ1	QBS Process Reference: SN3257QDYVRQ1	QBS Product Reference: SN74AVC2T45DDFR	QBS Package Reference: TPS76950QDBVRG4MQ1	QBS Package Reference: TLC3555QDDFRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/All/0	-	-	1/All/0	1/All/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	1/80/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	-	1/80/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/50/0	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/135/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	-	1/22/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	-	-	1/10/0	1/10/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	1/30/0	-	-
FTY	E6	Final Test Yield	-	-	1/All/0	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74AVC2T45DDFR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2602-013

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.